

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HYE YEON CHA</td> <td>01/23/2014</td> </tr> <tr> <td>YOUNG DO KWEON</td> <td>01/23/2014</td> </tr> <tr> <td>YOUNG SEUCK YOO</td> <td>01/23/2014</td> </tr> <tr> <td>HWAN SOO LEE</td> <td>01/23/2014</td> </tr> <tr> <td>WOON CHUL CHOI</td> <td>01/23/2014</td> </tr> </tbody> </table>		Name	Execution Date	HYE YEON CHA	01/23/2014	YOUNG DO KWEON	01/23/2014	YOUNG SEUCK YOO	01/23/2014	HWAN SOO LEE	01/23/2014	WOON CHUL CHOI	01/23/2014
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RECEIVING PARTY DATA													
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.												
Street Address:	150, MAEYEONG-RO, YEONGTONG-GU												
City:	SUWON, GYEONGGI-DO												
State/Country:	KOREA, REPUBLIC OF												
Postal Code:	443-743												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14175478</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14175478								
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CORRESPONDENCE DATA													
Fax Number:	(202)756-8087												
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NAME OF SUBMITTER:	STEPHEN A. BECKER												

PATENT

Signature:	/STEPHEN A. BECKER/
Date:	02/07/2014
Total Attachments: 2 source=ASSIGNMENT#page1.tif source=ASSIGNMENT#page2.tif	

(SAB)

Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|-----------------------------|----------------------------|
| (1) <u>CHA, Hye Yeon</u> | (5) <u>CHOI, Woon Chul</u> |
| (2) <u>KWEON, Young Do</u> | (6) _____ |
| (3) <u>YOO, Young Seuck</u> | (7) _____ |
| (4) <u>LEE, Hwan Soo</u> | _____ |

who have made a certain new and useful invention, hereby sell, assign and transfer unto

SAMSUNG Electro-Mechanics Co., Ltd.
150, Maeyong-ro, Yeongtong-gu,
Suwon, Gyeonggi-Do
Republic of KOREA
Postal Code: 443-743

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

POWER INDUCTOR AND MANUFACTURING METHOD THEREOF

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

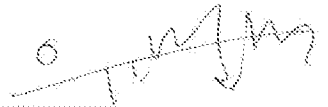
(b) for which an application for United States Letters Patent was executed on _____,

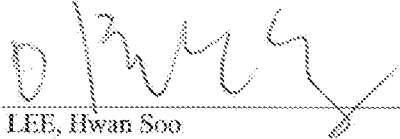
and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u>Cha Hye yeon</u> Name: CHA, Hye Yeon	<u>Jan 23, 2014</u>
2) <u>Young Do Kweon</u> Name: KWEON, Young Do	<u>Jan 23, 2014</u>

3)  Jan. 23, 2014
Name: YOO, Young Seuck

4)  Jan. 23, 2014
Name: LEE, Hwan Soo

5) Choi Woon Chul Jan. 23, 2014
Name: CHOI, Woon Chul